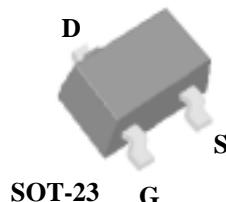


- ▼ Simple Drive Requirement
- ▼ Small Package Outline
- ▼ Surface Mount Device
- ▼ RoHS Compliant

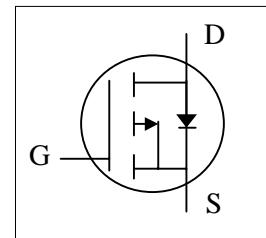


BV_{DSS}	-60V
$R_{DS(ON)}$	250m Ω
I_D	- 1.8A

Description

The Advanced Power MOSFETs from TY provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.

The SOT-23 package is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	- 60	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A=25^\circ\text{C}$	Continuous Drain Current ³	- 1.8	A
$I_D @ T_A=70^\circ\text{C}$	Continuous Drain Current ³	- 1.4	A
I_{DM}	Pulsed Drain Current ^{1,2}	-10	A
$P_D @ T_A=25^\circ\text{C}$	Total Power Dissipation	1.38	W
	Linear Derating Factor	0.01	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Unit
R_{thj-a}	Thermal Resistance Junction-ambient ³	Max. 90	$^\circ\text{C}/\text{W}$

Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-60	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to 25°C , $I_{\text{D}}=-1\text{mA}$	-	-0.04	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-1.8\text{A}$	-	200	250	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-1.4\text{A}$	-	240	300	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=-250\mu\text{A}$	-1	-	-3	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$, $I_{\text{D}}=-1\text{A}$	-	2	-	S
I_{DSS}	Drain-Source Leakage Current ($T_j=25^\circ\text{C}$)	$V_{\text{DS}}=-60\text{V}$, $V_{\text{GS}}=0\text{V}$	-	-	-10	μA
	Drain-Source Leakage Current ($T_j=70^\circ\text{C}$)	$V_{\text{DS}}=-48\text{V}$, $V_{\text{GS}}=0\text{V}$	-	-	-25	μA
I_{GSS}	Gate-Source Leakage	$V_{\text{GS}}=\pm 20\text{V}$	-	-	± 100	nA
Q_g	Total Gate Charge ²	$I_{\text{D}}=-1\text{A}$	-	6	10	nC
Q_{gs}	Gate-Source Charge		-	1	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge		-	3	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time ²	$V_{\text{DS}}=-30\text{V}$	-	8	-	ns
t_r	Rise Time	$I_{\text{D}}=-1\text{A}$	-	5	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time	$R_G=3.3\Omega$, $V_{\text{GS}}=-10\text{V}$	-	22	-	ns
t_f	Fall Time	$R_D=30\Omega$	-	3	-	ns
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	510	810	pF
C_{oss}	Output Capacitance	$V_{\text{DS}}=-25\text{V}$	-	50	-	pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	40	-	pF
R_g	Gate Resistance	$f=1.0\text{MHz}$	-	6.4	9.6	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$I_S=-1.2\text{A}$, $V_{\text{GS}}=0\text{V}$	-	-	-1.2	V
t_{rr}	Reverse Recovery Time ²	$I_S=-1\text{A}$, $V_{\text{GS}}=0\text{V}$,	-	30	-	ns
Q_{rr}	Reverse Recovery Charge	$dI/dt=100\text{A}/\mu\text{s}$	-	38	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 3.Surface mounted on 1 in² copper pad of FR4 board, $t \leq 10\text{sec}$; $270^\circ\text{C}/\text{W}$ when mounted on Min. copper pad.